

**IN THE CLAIMS:**

**Claims 1-15 (Presently Cancelled)**

**16. (New)** A process for the production of a solid first sheet material, comprising the step of heating and applying pressure to:

(a) at least one second sheet comprising a nonwoven fabric of short high tensile modulus fibers and a thermoplastic polymer having a low moisture absorption,

or

at least one third sheet comprising a nonwoven fabric of a short high tensile modulus fiber and at least one fourth sheet comprising a thermoplastic polymer; and

(b) at least one metal sheet

to form wherein said liquid crystalline polymer fills essentially all voids between said high tensile modulus fibers so that said sheet has an apparent density which is at least about 75% of its calculated density.

**17. (New)** The process as recited in claim 16 wherein said apparent density is at least about 90% of said calculated density.

**18. (New)** The process as recited in claim 17 wherein said thermoplastic polymer is a liquid crystalline polymer or a perfluoropolymer.

**19. (New)** The process as recited in claim 16 wherein said high tensile modulus fiber is an aramid.

**20. (New)** A circuit board produced by the process of claim 16.